

In the Claims:

Please amend the Claims as follows:

Claim 1. (Currently Amended) ~~A method Method~~ to produce electronic components with closely adjacent electrodes on a substrate such that ~~characterized in that~~ the structuring of the electrodes is achieved using the following steps:

- a) structuring a photo lacquer ~~is structured~~ on ~~a the~~ substrate with overlapping edges;
- b) depositing a metal vapor ~~is deposited~~ onto the substrate and the structured photo lacquer;
- c) applying an insulator ~~is applied~~ over the deposited metal vapor, structured photo lacquer, and substrate surface thus produced;
- d) etching the insulator ~~is etched, whereby~~ such that flat edges are formed on the overlapping edges of the photo lacquer as an inverse of the overlaps.

Claim 2. (Currently Amended) ~~A method Method~~ to produce electronic components with closely adjacent electrodes on a substrate such that ~~characterized in that~~ the structuring of the electrodes is achieved using the following steps:

- a) depositing a metal layer ~~is deposited~~ onto the substrate;
- b) structuring a photo lacquer ~~is structured~~ on the metal layer;
- c) etching the ~~exposed~~ metal layer ~~is etched, whereby~~ such that overhangs ~~arise~~ are formed in the photo lacquer by means of controlled undercutting of the metal;
- d) exposing the ~~The~~ surface thus produced ~~is exposed~~ to metal vapor;
- e) removing the photo lacquer with its metal layer ~~is removed~~.

Claim 3. (Currently Amended) The method of claim 2 ~~Method to produce electronic components with closely adjacent electrodes on a transparent substrate characterized in that~~ further comprising:

- a) ~~The electrodes are structured on the substrate as in Claim 2;~~
- ba) depositing a ~~A~~ transparent organic semi-conductor and a transparent insulator ~~are deposited on the surface thus produced~~,
- eb) depositing a ~~A~~ second photo lacquer is deposited on an ~~the~~ upper side, and performing photo lithography ~~is performed on an the~~ underside,
- dc) depositing a metal vapor ~~is deposited~~ onto the surface thus produced,

ed) removing the remaining photo lacquer with its metal layer is removed,

fe) the electronic component is completed by etching the at least one contact contact[s] until they are it is exposed.

Claim 4. (Currently Amended) The method of claim 2 further comprising Method to produce electronic components with closely adjacent electrodes on a substrate characterized in that:

a) The electrodes are structured on the substrate as in Claim 2;

ba) etching holes Holes or grooves are etched into the substrate at those positions without metal,

eb) depositing a A second thin metal layer is deposited,

dc) applying an An insulator is applied,

ed) etching the The insulator on an the upper side of the substrate is etched;

fe) applying an An organic semi-conductor is applied and sealing the surface is sealed,

gf) exposing at least one The buried gate[s] are exposed gate using a photolithographic process.